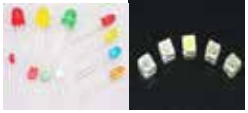

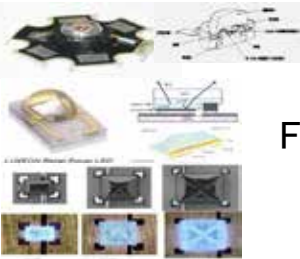






LED Package Process の分析

Package process	Level 1				Level 2		Level 3
Item	Die-bond	Wire-bond	Lead-frame	Package	SMT	PCB	Lighting
 Sapphire base	●	●	PLCC	●	●	●	●
 Vertical	●	●	PLCC	●	●	●	●
 Flip-chip	BGA	●	Sub-mount +K1	●	●	●	●
	BGA	N/A	Sub-mount	●	●	●	●
	Gold-Tin	N/A	Sub-mount	●	●	●	●
 COB	●	●	●	●	●	●	●
 WLCSP	N/A	N/A	N/A	N/A	SMT	●	●

●●●電極上の金PAD厚みは必須強化(拉力:10G、推力:40g以上)